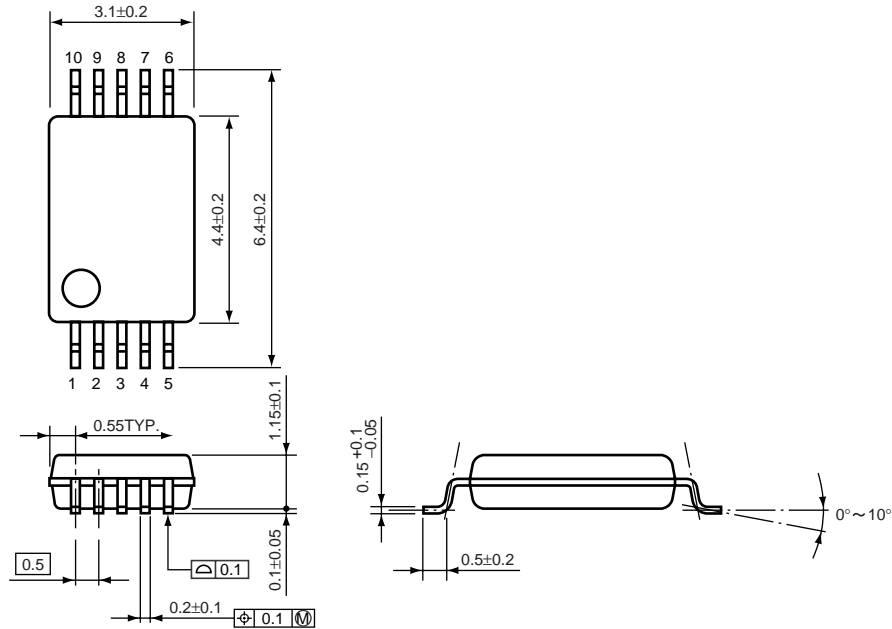


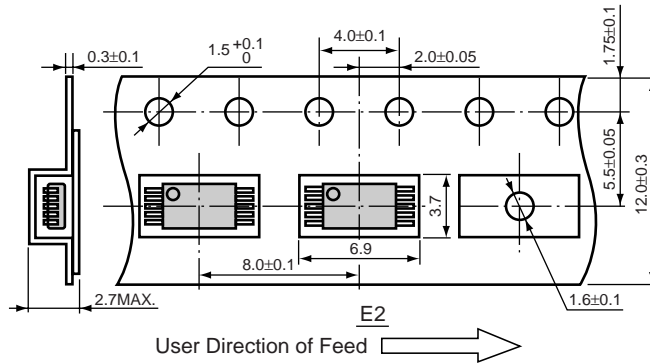
• SSOP-10

Unit: mm

PACKAGE DIMENSIONS

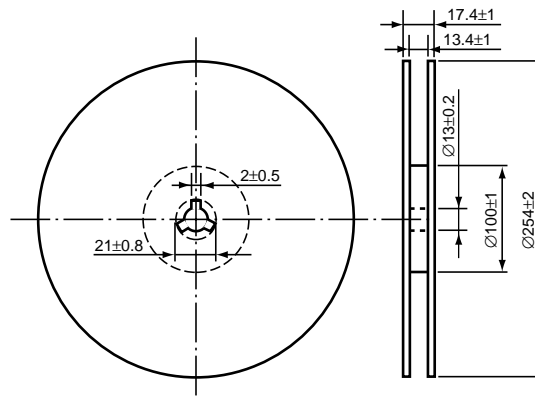


TAPING SPECIFICATION



TAPING REEL DIMENSIONS

(1reel=2000pcs)



## POWER DISSIPATION (SSOP-10)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

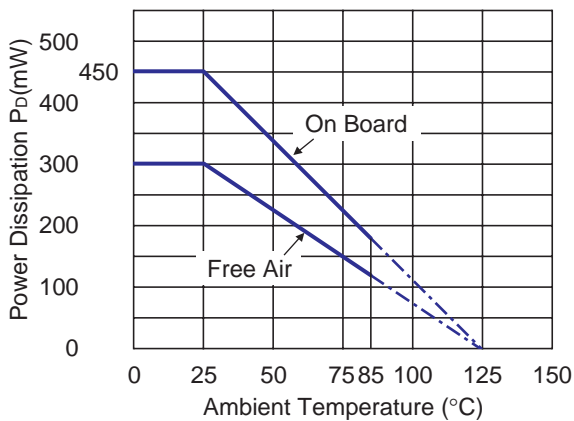
### Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plactic (Single sided)
Board Dimensions	10mm × 10mm × 1.6mm
Copper Ratio	Approx. 10%
Through-hole	-

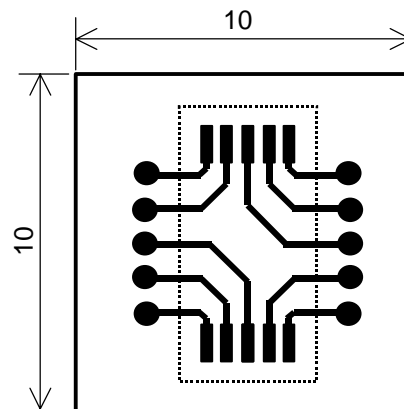
### Measurement Result

( $T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$ )

	Standard Land Pattern	Free Air
Power Dissipation	450mW	300mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.45W=222^{\circ}C/W$	333 $^{\circ}C/W$



Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

## RECOMMENDED LAND PATTERN

